

In the Claims:

The following listing of claims supercedes and replaces all prior versions in the patent application.

Claims 1-45 (Previously cancelled)

46. (Currently Amended) A double-sided printed wiring board comprising:

an insulator substrate having at least first and second generally parallel surfaces
and a blind via extending at least partly therethrough from said first surface,
the blind via having a sidewall;

a cured mass of a flowable conductive material filling said blind via and having an
end located adjacent to ~~at least one side~~ the first surface of said insulator
substrate; and

a conductive pad disposed over the cured mass of flowable conductive material and
being in electrical communication with the cured mass of flowable conductive
material.

47. (Previously Added) The board according to claim 46, wherein said cured mass of
flowable conductive material is selected from the group consisting of conductive inks,
conductive pastes, and conductive adhesives.

48. (Previously Added) The board according to claim 46, wherein said conductive pad comprises copper.

49. (Previously Added) The board according to claim 48, wherein said conductive pad has a thickness greater than approximately 0.2 mils.

50. (Currently Amended) A printed circuit board (PCB) ~~having one or more strata and~~ comprising:

a substrate having at least first and second generally parallel surfaces and a blind via extending from said first surface, the blind through at least one of said strata, said via having a sidewall;

a first conductive material disposed on at least one side of said one of said strata layer extending over substantially all of the first surface such that said via ~~has~~ still maintains an opening, said first conductive material comprising electrolytically deposited copper having a substantially uniform thickness exceeding approximately 0.2 mils;

a second conductive material disposed in said opening to substantially fill said blind via opening; and

a third conductive material disposed on said first conductive material layer on said

~~at least one side of said one of said strata and on~~ first surface, and over an
end portion of said second conductive material in said opening.

51. (Previously Added) The board according to claim 50, wherein said second conductive material is cured flowable conductive material.

52. (Previously Added) The board according to claim 51, wherein said second conductive material is a conductive ink.

53. (Previously Added) A circuit board comprising:

a substrate having at least first and second generally parallel surfaces and a blind via extending from the first surface, the blind via having a sidewall;

a first conductive layer extending over substantially all of the first surface;

a conductive material positioned within the blind via, the conductive material plugging the blind via such that the blind via has no opening extending from the first surface; and

a second conductive layer extending over substantially all of the first conductive layer on the first surface, and over an end portion of the conductive material positioned within the blind via.

54. (Previously Added) The circuit board of claim 53 wherein the first and second surfaces are exterior surfaces of the substrate.

55. (Previously Added) The circuit board of claim 53 wherein the first conductive layer comprises copper.

56. (Previously Added) The circuit board of claim 55 wherein the second conductive layer comprises copper.

57. (Previously Added) The circuit board of claim 53 wherein the conductive material positioned within the via is selected from the group consisting of conductive inks, conductive pastes, and conductive adhesives.

58. (Previously Added) The circuit board of claim 57 wherein the conductive material is a conductive ink.

59. (Previously Added) The circuit board of claim 58 wherein the conductive ink comprises at least one of silver, copper, and a noble metal.

60. (Previously Added) The circuit board of claim 53 wherein the first and second conductive layers are adapted to be etched to thereby form a conductive pad positioned on the conductive material plugging the via.